

Haichao Zhu

ERATO Kawahara Project,
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Experience

University of Tokyo, ERATO Kawahara Universal Information Project 04/2017 – Present
Technical Assistant

Advisor: [Yoshihiro Kawahara](#)

- Provided technical supports to researchers, artists and students.
- Finished a fully functional 3D printing system for food material.
- Constructed a Wireless-Power-Transfer system.

Hasso Plattner Institut (German), HCI Lab 04/2016 - 10/2016
Research Assistant

Advisor: [Patrick Baudisch](#)

- Completed a machine controlling system with both hardware drivers and a GUI program based on JAVA.
- Conducted research for a Self-Driving Robot system.

Microsoft Research Asia, HCI/Robotic Group 11/2016 – 03/2017
Research intern 08/2015 – 04/2016

Advisor: [Fukumoto Masaaki](#)

- Conducted research about a wrist-worn device that enable universal input by recognizing bio-acoustic signals using machine learning algorithms.

Tsinghua University, Ubiquitous Computing 07/2014 – 06/2015
Research Assistant

Advisor: [Yuanchun Shi](#)

- Developed a EMF data collecting system, which contributed to a whole-body gesture recognition research project.
- Contributed on paper surveys and experiment assistants.

Beijing University of Posts and Telecommunications, Innovation Lab 08/2013 – 08/2015
Student

- Participated various contests and had won various awards.

Education

Beijing University of Posts and Telecommunications 08/2012 - Present
Bachelor of Telecommunication Engineering

Awards

1st Prize in US-China Maker Contest

1st Prize in International Microsoft Imagine Cup in China

1st Prize in National LabVIEW Virtual Instrument Contest

1st Prize in National Collegiate Smart Car Contest

2nd Prize in Intel Cup Undergraduate Electronic Invitational Contest

2nd Prize in Beijing Electronic Design Contest

3rd Prize in Xiaomi Innovation maker contest

Scholarships in Beijing University of Posts and Telecommunications

Skills

Language

Chinese, English, Japanese (Entry Level)

Software

Language: C/C++, C#, Java, Python

Platform: Android, IOS, Web (Bootstrap, Vue, React), Embedded Linux, Arduino, Android Wear

Machine Learning: TensorFlow, HTK(Hidden-Markov-Toolkit)

Hardware

Electrical: DSP, FPGA, Signal Processing, RF Circuit Design, EM Simulation

Mechanical: 3D Modelling, Fabrication

Prototyping: 3D Printing, Laser Cutter, CNC, PCB